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A

B

C

D

Layer	Name	Material	Thickness	Constant	Board Layer Stack	Board Layer Stack
1	Top Overlay					
2	Top Solder	Solder Resist	0.40mil	3.5		
3	Top Layer	Copper	1.40mil			
4	Dielectric1	FR-4 High Tg	59.20mil	4.8		
5	Bottom Layer	Copper	1.40mil			
6	Bottom Solder	Solder Resist	0.40mil	3.5		
7	Bottom Overlay					

Symbol	Count	Hole Size	Plated	Hole Type	Hole Length
☆	107	7.87mil (0.200mm)	PTH	Round	-
◇	21	12.00mil (0.305mm)	PTH	Round	-
⊠	228	16.00mil (0.406mm)	PTH	Round	-
⊙	14	32.00mil (0.813mm)	NPTH	Slot	200.00mil (5.080mm)
○	50	40.00mil (1.016mm)	PTH	Round	-
□	40	43.31mil (1.100mm)	PTH	Round	-
▽	4	47.24mil (1.200mm)	PTH	Round	-
	464 Total				

Slot definitions : Routed Path Length = Calculated from tool start centre position to tool end centre position.
Hole Length = Routed Path Length + Tool Size = Slot length as defined in the PCB layout

90.00

108.00mm

Drill Table

FOR 7.874MIL DRILL +0/-7.874MIL
FOR 12MIL DRILL +0/-12MIL
FOR 16MIL DRILL +0/-16MIL
FOR PTH DRILL +/-3MIL
FOR NPTH DRILL +/-2MIL

ALL ARTWORK VIEWED FROM TOP SIDE

BOARD #: TIDA-010008_IO-Power+protection_BIDIR

LAYER NAME = Drill Drawing

TID #: 010008

PLOT NAME = Fabrication Drawing

GENERATED : 4/29/2019 3:05:00 PM

TEXAS INSTRUMENTS

TEXAS INSTRUMENTS (TI) and/or its licensors do not warrant the accuracy or completeness of this specification or any information contained therein. TI and/or its licensors do not warrant that this design will meet the specifications, will be suitable for your application or fit for any particular purpose, or will operate in an implementation. TI and/or its licensors do not warrant that the design is production worthy. You should completely validate and test your design implementation to confirm the system functionality for your application.

DESIGN INFORMATION

BOARD SIZE (REFER ALSO ARRAY/PANEL PROFILING INFORMATION)
108MM X 90MM

Number of Layers : 2
MIN. TRACK WIDTH: 10 MIL
MIN. CLEARANCE: 7.2 MIL
MIN. VIA DRILL SIZE: 7.874 MIL

MINIMUM ANNULAR RING 6 MIL (0.1524 mm) EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL

MATERIAL:
☐ FR-408 ☒ FR-4 High Tg ☐ OTHER

THICKNESS: ☒ 63 MIL (1.6mm) +/-10% ☐ OTHER

TOLERANCE: ☒ ANSI IPC-6012 TYPE 3 CLASS 2
☐ OTHER +/-

BOW & TWIST: ☒ ANSI IPC-6012 TYPE 3 CLASS 2
☐ OTHER +/-

COPPER THICKNESS (FINISHED):
OUTER: ☒ 1.4MIL (1oz) ☐ 2MIL (1.4oz) ☐ 2.8MIL (2oz)
INNER SIGNAL: ☐ 1.4MIL (1oz) ☐ 2.8MIL (2oz) ☒ N/A

DRILLING:
REFERENCE: ☒ AS SHOWN ☒ NC_DRILL FILES
PTH MIN COPPER THICKNESS: ☒ 1MIL ☐ OTHER

BOARD FINISH:
SILKSCREEN: ☒ TOP ☒ BOTTOM
SILKSCREEN COLOR: ☒ WHITE ☐ OTHER
SOLDER RESIST COLOR:
☒ GREEN ☐ BLUE ☐ OTHER

SURFACE FINISH: ☒ IMMERSION GOLD (ENIG) ☐ ENEPIG
☐ IMM. TIN/SILVER OR EQUIV ☐ OTHER

ARRAY/PANEL: ☐ CUT AND TRIM PER MECH LAYER 1
☐ N.C. ROUTE ☒ V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBs TO MEET OR EXCEED THE REQUIREMENTS OF:
☒ ANSI IPC-A-600F CLASS -> ☐ 1 ☒ 2 ☐ 3
☒ UL 94V-0 ☒ RoHS ☐ OTHER PER ORDER

ADDITIONAL REQUIREMENTS: VIA TENTING: YES ☐ NO ☒
MICROSECTION: ☐ YES IMPEDANCE CONTROL: YES ☐ NO ☒
BARE BOARD ELEC. TEST: ☐ NONE ☒ REQUIRED ☐ PER ORDER
MANUFACTURER'S UL: ☐ RAIL ☐ METAL ☒ SILK

TEXAS INSTRUMENTS

PROJECT TITLE:
TIDA-010008_IO-Power+protection_BIDIR

DESIGNED FOR:
Public Release

FILE NAME:
TIDA-010008_IO-Power+protection_BIDIR.PcbDoc

ENGINEER:
Greenivasa

LAYOUT BY:
Avinash N

SCALE: 1.00

ALTUM DESIGNER VERSION:
18.1.9.240

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